

# MA27D30

## Silicon epitaxial planar type

For super high speed switching

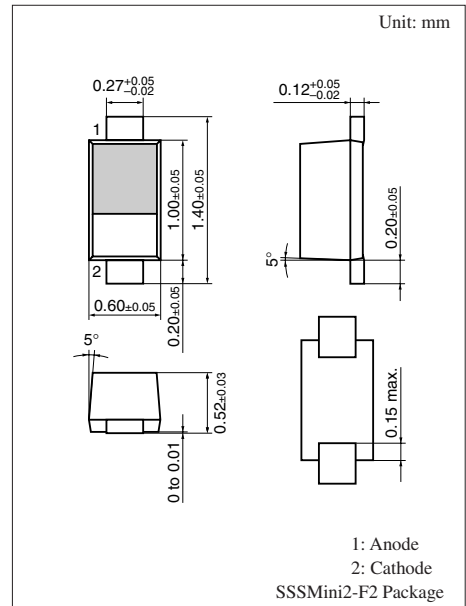
### ■ Features

- Small reverse current:  $I_R < 2 \mu\text{A}$  (at  $V_R = 30 \text{ V}$ )
- Optimum for high frequency rectification because of its short reverse recovery time  $t_{rr}$ .

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	30	V
Repetitive peak reverse voltage	$V_{RRM}$	30	V
Forward current (Average)	$I_{F(AV)}$	100	mA
Peak forward current	$I_{FM}$	200	mA
Non-repetitive peak forward surge current *	$I_{FSM}$	1	A
Junction temperature	$T_j$	125	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +125	$^\circ\text{C}$

Note) \* : The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



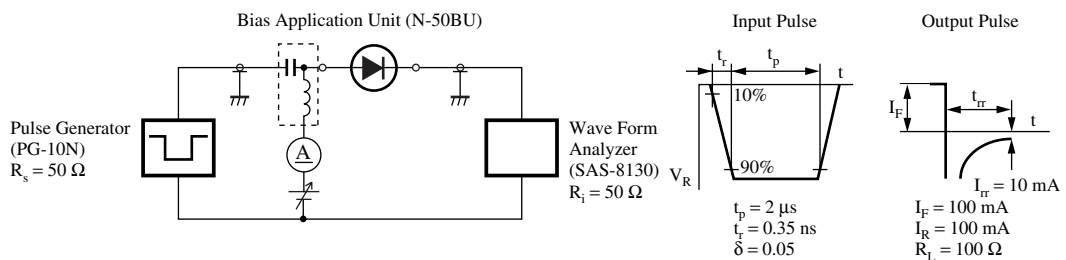
Marking Symbol: 8N

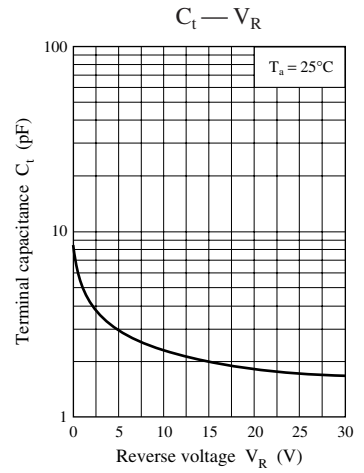
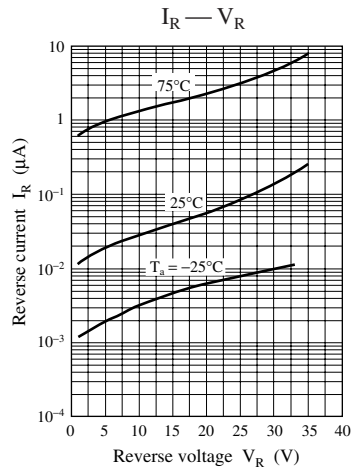
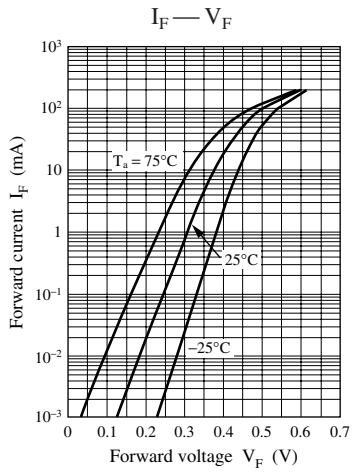
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_{F1}$	$I_F = 10 \text{ mA}$		0.38	0.44	V
	$V_{F2}$	$I_F = 100 \text{ mA}$		0.51	0.58	V
Reverse current	$I_{R1}$	$V_R = 10 \text{ V}$			0.3	$\mu\text{A}$
	$I_{R2}$	$V_R = 30 \text{ V}$			2	$\mu\text{A}$
Terminal capacitance	$C_t$	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$		9		pF
Reverse recovery time *	$t_{rr}$	$I_F = I_R = 100 \text{ mA}$ $I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$		1		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 250 MHz
4. \*:  $t_{rr}$  measurement circuit





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